

# YT6180

## Pick & Place Test Handler

### Capability & Specification

Test Site	YT6180: 1*2/1*4/2*2/2*4/2*8
Applicable Device Type	QFP、LQFP、PLCC、SOP、TSOP、BGA、QFN、uBGA、PGA and FBGA
Device Size	3*3~50.0*50.0mm
Index Time	≥0.9Sec.
Throughput	Device Size:3x3mm~7x7mm,UPH Max:15000~10000 (2x4 mode)
Jam Rate	1/5000
Transfer Hand	8
Tray Type	EIA/JDEC Tray
Input Tray	Auto Input Tray:1、Empty Tray:2
Output Tray	Auto output tray: 3 for output devices Fix Tray: 3 for output devices
Binning	Max.: 12 Bins Auto output Tray: 3 Fix output Tray: 3 (each Fix output tray can set partition from 1~3 bin)
IC Contact	Fast/Slow/Drop-down Contact mode
Index Arm	Rotation
Detect Shuttle IC	Inductive contrast sensor
Temperature	Ambient, +50°C~ +90°C +/- 2°C, +90°C~ +135°C +/- 3°C(Option)
Test Interface	GPIB Interface(Standard), TTL(option)/RS-232 Interface(option)
Operation	Windows 7
Net Weight	Around 1200KG
Dimension	2100mm(L)x1700 mm (W) x 2000 mm (H)
Power Requirement	AC 220V/, 50~60Hz, Single Phase
Compressed Air	Dry Air of /cm <sup>2</sup> (0.49Mpa) FLOW: static stats 280 L/min (static), dynamic 220 L/min (dynamic)
Double Chip Detect	CCD

ALL SPECIFICATIONS ARE SUBJECT TO CHANGE WITHOUT NOTICE



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